



H3C UniServer R6700 G3 Server

High-density rack server designed for core business scenarios

Powered by Intel® processors

Release Date: August, 2021



New H3C Technologies Co., Limit

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Industrial-leading performance improves data center productivity

- 4 sockets of the recent Intel® Xeon® Scalable Processors
- 8 x single-slot wide GPU modules
- 24 x Intel® Optane™ DC Persistent Memory Module

Favorable Scalability and Rich combinations.

- 26 x SFF Drives
- 18 x NVMe Drives
- 11 x PCI-E 3.0 Slots
- 2U High-density rack

Enterprise-grade RAS

- High RAS features
- Redundant Components

Effective Security Design

- TPM/TCM
- Chassis Intrusion Detection

Design for High Reliability, High performance, High Density

New generation H3C UniServer R6700 G3 adopt a high density architecture to provide outstanding performance with 4 sockets and achieve high reliability and flexibility within only 2U rack. This model supports up to 26 SFF drives include optional 18 NVMe SSD drives. R6700 G3 server features Enterprise-grade RAS make it a decent choice for core workload , virtualization, Database, data-processing and high-density computing application.

H3C UniServer R6700 G3 utilizes the most recent 2nd generation Intel® Xeon® scalable processor. With 11 x PCIe3.0 I/O slot to reach excellent IO scalability. 94%/96% power efficiency and 5 ~ 45°C standard Operating temperature Provide users with higher energy efficiency returns.

You can use the R6700 G3 to support the following services:

- Virtualization — Support multiple types of workloads on a single server to save space
- Big Data — Manage exponential growth of structured, unstructured, and semi-structured data.
- Applications centered on storage — Remove I/O bottleneck and improve performance
- Data warehouse/analysis — Query data on demand to help service decision
- Customer relationship management (CRM) — Help you to gain comprehensive insights into business data to improve customer satisfaction and loyalty
- Enterprise resource planning (ERP) — Trust the R6700 G3 to help you manage services in real time
- Virtual desktop infrastructure (VDI) — Deploys remote desktop service to bring great office agility and enable telecommuting with any device anywhere anytime
- High-performance computing and deep learning — Provide 3 dual-slot wide GPU modules in a 2U footprint, meeting the requirements of machine learning and AI applications

The R6700 G3 supports Microsoft® Windows® and Linux operating systems, as well as VMware and H3C CAS and can operate perfectly in heterogeneous IT environments.

Detailed Specification

Computing	4 × Intel® Xeon® Scalable processors (Up to 28 cores and maximum 205 W power consumption)
Memory	48 × DDR4 DIMMs, 6.0 TB (maximum) (Up to 2933 MT/s data transfer rate and support for both RDIMM and LRDIMM) (Up to 24 Intel® Optane™ DC Persistent Memory Module.(DCPMM))
Storage controller	Embedded RAID controller (SATA RAID 0, 1, 5, and 10) Standard PCIe HBA cards and storage controllers (Optional)
FBWC	8 GB DDR4-2133MHz
Storage	Maximum Front 24SFF + rear 2SFF, Support SAS/SATA HDD/SSD Drives Maximum 16 front UniBay Slots, Rear 2 × UniBay Slots, Support SAS/SATA/NVMe Drives SATA M.2 SSDs (Optional) 2 × SD internal slots (Optional)
Network	1 × onboard 1 Gbps management network port 2 × onboard 1 Gbps network port Support sLOM 4 × 1GE copper ports or 2 × 10GE/2 × 25GE fiber ports, sLOM support NCSI function Support Standard PCIe 3.0 Ethernet Adapters Support 10/25/40/100GE/IB/OPA High-performance Ethernet Adapter, Support FC-HBA SAN Adapter
PCIe slots	11 × PCIe 3.0 slots (one dedicated slot for Ethernet adapter, 6 × FH slots, 8 × PCIe x16 slots)
Ports	Front VGA connector Rear VGA connector and serial port(RJ-45) 5 × USB 3.0 connectors (one at the front, two at the rear, and two in the server) 1 × USB 2.0 front connector SFF Liquid Crystal Display Module (Optional)
GPU	8 × single-slot wide GPU modules
Optical drive	External optical disk drive (Optional)
Management	HDM (with dedicated management port) and H3C FIST, Support LED/LCD screen*diagnostic panel
Security	Support Chassis Intrusion Detection TPM2.0
Power supply	Platinum 1600W(supports 1+1 redundancy) , 800W –48V/336V DC power supplies (1+1 redundancy) Hot swappable fans (supports redundancy)
Standards	CE, UL, FCC, VCCI, EAC, etc.
Operating temperature	5°C to 45°C (41°F to 113°F) The maximum operating temperature varies by server configuration. For more information, see the technical documentation for the device.
Dimensions (H × W × D)	2U Height Without a security bezel: 87.5 × 445.4 × 748 mm (3.44 × 17.54 × 29.45 in) With a security bezel: 87.5 × 445.4 × 769 mm (3.44 × 17.54 × 30.28 in)

*Configuration may vary, refer to related user guide for more detail



The Leader in Digital Solutions

New H3C Technologies Co., Limited

Beijing Headquarters
Tower 1, LSH Center, 8 Guangshun South Street, Chaoyang District, Beijing, China
Zip: 100102
Hangzhou Headquarters
No.466 Changhe Road, Binjiang District, Hangzhou, Zhejiang, China
Zip: 310052
Tel: +86-571-86760000

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